

What is claimed is:

1. A method of attaching a semiconductor die to a lead frame comprising: providing a source of snap curable adhesive; providing a source of lead frames, each lead frame having an attaching surface; providing a source of semiconductor die, each semiconductor die having an active surface; applying said snap curable adhesive to a portions of one of the lead frames; and contacting said active surface of one of the semiconductor die with said portions of one of the lead frames having said snap curable adhesive thereon.

- 2. The method of claim 1, further including the step of: heating one of said semiconductor die.
- 3. The method of claim 1, wherein said snap curable adhesive includes a snap curable epoxy having a cure time of about one second.
- 4. The method of claim 1, wherein said snap curable adhesive includes an adhesive having a cure time of substantially one minute or less.
- 5. The method of claim 1, wherein said snap curable adhesive is applied to the portions of said one of the lead frames using a roller.
- 6. A method of attaching a semiconductor die to a lead frame comprising: providing a source of snap curable adhesive; providing a source of lead frames, each lead frame having an attaching surface; providing a source of semiconductor die, each semiconductor die having an active surface; applying said snap curable adhesive to a portions of the active surface of one of said

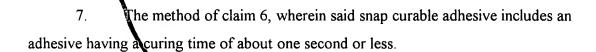
semiconductor die; and contacting said curable adhesive with portions of one of said lead frames.

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8. The method of claim 6, wherein said snap curable adhesive is applied to said active surface of one of said semiconductor devices in a predetermined pattern.